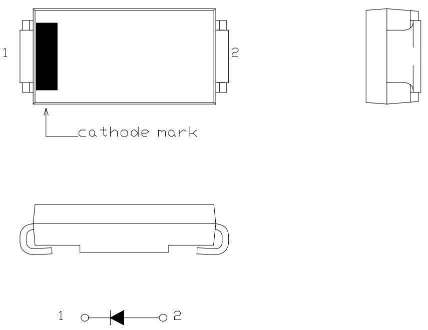
Nihon Inter Electronics Corporation

SBD Type : NSH03A10

FEATURES

- **FLAT-PAK** Surface Mounting Device
- Low Forward Voltage Drop
- Low Power Loss,High Efficiency
- High Surge Capability
- Packaged in 16mm Tape and Reel
- Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight:0.16g

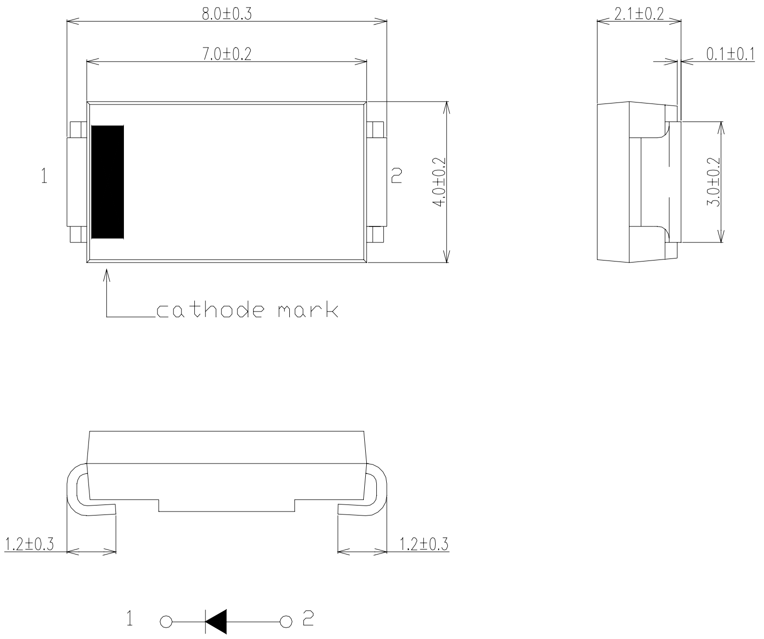
Rating	Symbol	NSH03A10			Unit
Repetitive Peak Reverse Voltage	V_{RRM}	100			V
Average Rectified Output Current	I_o	1.5	Ta=25℃ *1	50Hz Half Sine Wave Resistive Load	A
		3.0	Tl=112℃		
RMS Forward Current	$I_{F(RMS)}$	4.71			A
Surge Forward Current	I_{FSM}	60	50Hz Half Sine Wave,1cycle Non-repetitive		A
Operating JunctionTemperature Range	T_{jw}	-40 to +150			℃
Storage Temperature Range	T_{stg}	-40 to +150			℃

Electrical • Thermal Characteristics

Characteristics		Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current		I_{RM}	Tj= 25℃, V_{RM}= V_{RRM}	-	-	1	mA
Peak Forward Voltage		V_{FM}	Tj= 25℃, I_{FM}= 3.0A	-	-	0.85	V
Thermal Resistance	Junction to Ambient	$Rth_{(j-a)}$	Alumina Substrate Mounted *1	-	-	89	℃ /W
	Junction to Lead	$Rth_{(j-l)}$	-	-	-	13	

*1 Alumina Substrate Mounted (Soldering Lands=2x3.5mm,Both Sides)
(Tl: Lead Temperature)

NSH03A10 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD